



# Product Change Notification

**Change Notification #:** 116219 - 00  
**Change Title:** Select Intel® SSD DC P4500 Series and Intel® SSD DC P4600 Series, PCN 116219-00, Product Design, VCC Droop HW improvement  
**Date of Publication:** May 08, 2018

## Key Characteristics of the Change:

Product Design

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	June 8, 2018
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## Description of Change to the Customer:

The Intel® SSD DC P4500 Series and Intel® SSD DC P4600 Series products listed in the Products Affected table will undergo the following changes:

Capacitors have been added / removed / changed on the Intel® SSD DC P4500 and DC P4600 AIC form factor Series to reduce possible chance of drive failure caused by voltage droop on the NAND media. This was only observed during a corner case involving the combination of a heavy workload, out of spec voltage was applied to the drive, and during an unplanned power loss. Intel has validated the fix and does not expect any customer impact or action required at this time.

1. Remove capacitor IPN 108426-206 from location C69 and C70.
2. Add capacitor IPN 108426-206 at location C75 and C76.
3. Change location C563 from capacitor IPN A36096-112 to H94452-001. Capacitance at location C580 changed from 4.7uF to 22uF.
4. Change location C580 from capacitor IPN 644066-151 to 644066-120. Capacitance at location C563 changed from 0.1uF to 0.47uF.

## Customer Impact of Change and Recommended Action:

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

## Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#	Pre Change PBA	Post Change PBA
Intel® SSD DC P4500 Series (4.0TB, 1/2 Height PCIe 3.1 x4, 3D1, TLC) Generic 10 Pack	SSDPEDKX040T710	954777	H91115-104	H91115-105
Intel® SSD DC P4500 Series (4.0TB, 1/2 Height PCIe 3.1 x4, 3D1, TLC) Generic Single Pack	SSDPEDKX040T701	950685	H91115-104	H91115-105
Intel® SSD DC P4600 Series (2.0TB, 1/2 Height PCIe 3.1 x4, 3D1, TLC) Generic 10 Pack	SSDPEDKE020T710	954826	J29561-104	J29561-105
Intel® SSD DC P4600 Series (2.0TB, 1/2 Height PCIe 3.1 x4, 3D1, TLC) Generic Single Pack	SSDPEDKE020T701	954825	J29561-104	J29561-105
Intel® SSD DC P4600 Series (4.0TB, 1/2 Height PCIe 3.1 x4, 3D1, TLC) Generic 10 Pack	SSDPEDKE040T710	954828	J29565-104	J29565-105
Intel® SSD DC P4600 Series (4.0TB, 1/2 Height PCIe 3.1 x4, 3D1, TLC) Generic Single Pack	SSDPEDKE040T701	954827	J29565-104	J29565-105

## PCN Revision History:

**Date of Revision:**

May 8, 2018

**Revision Number:**

00

**Reason:**

Originally Published PCN



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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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